EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	821	361/803.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:08
L2	9	electrical adj power adj circuit adj assembly	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:09
L3	1	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:10
L4	357	insulated adj metal adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:10
L5	4	1 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:10
L6	248966	printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:10
L7	444	1 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:11
L8	2	4 and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:11

EAST Search History

L9	35853	6 and capacitors	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:12
L10	12244	9 and filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:12
L11	20	4 and 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:12
L12	1	9 and conductive adj circuit adj foil adj layers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:23
L13	1	6 and conductive adj circuit adj foil adj layers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:13
L14	1	1 and conductive adj circuit adj foil adj layers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:14
L15	2117753	"7046535" b2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 11:14
L16	0	("7046535b2").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/17 11:15

L17	2	("7046535").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/17 11:16
L18	2	("6661659").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/17 11:16
L19	1	conductive adj circuit adj foil adj layers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:09
L20	0	361/7759,802,756	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:09
L21	0	361/759,802,756	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:10
L22	702	361/759.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:10
L23	662	361/802.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:10
L24	465	361/756.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:10

EAST Search History

L25	60	22 and 23 and 24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:10
L26	1	1 and 25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:22
L27	129	((insulated adj metal Adj substrate) and IMS)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:28
L28	98557	(((insulated adj metal Adj substrate) and IMS)and (printed adj circuit adj board) (PCB))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:29
L29	36407	9(((insulated adj metal Adj substrate) and IMS)and (printed adj circuit adj board) (PCB))and IMS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:30
L30	35853	9(((insulated adj metal Adj substrate) and IMS)and (printed adj circuit adj board) (PCB))and IMS and (metal adj substrate) and (Electrically adj non-conductive adj board adj layers)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:30
L31	1	(((insulated adj metal Adj substrate) and IMS)and (printed adj circuit adj board) (PCB))and IMS and (metal adj substrate) and (Electrically adj non-conductive adj board adj layers)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 12:30